

2N3700HR

Hi-Rel 80 V - 1 A NPN bipolar transistor

Features

BV _{CEO}	80 V
I _C (max)	1 A
H _{FE} at 10 V - 150 mA	> 100
Operating temperature range	-65°C to +200°C

- Hi-Rel NPN bipolar transistor
- Linear gain characteristics
- ESCC qualified
- European preferred part list EPPL
- 100 krad low dose rate
- Radiation level: lot specific total dose contact marketing for specified level

Description

The 2N3700HR is a silicon planar epitaxial NPN transistor in TO-18 and LCC-3 packages. It is specifically designed for aerospace Hi-Rel applications and ESCC qualified according to the 5201-004 specification. In case of conflict between this datasheet and ESCC detailed specification, the latter prevails.

Table 1.Device summary



Figure 1. Internal schematic diagram



Order codes	ESCC part num.	Qual. level	Rad level	Packages	Lead finish	Mass (g)	EPPL
2N37000UB1	-	Eng. model		LCC-3UB	Gold	0.06	-
2N37000UBSW	5201/004/07	ESCC flight	100 krad	LCC-3UB	Solder dip	0.06	Y
2N37000UB06	5201/004/06	ESCC flight		LCC-3UB	Gold	0.06	-
2N37000UB07	5201/004/07	ESCC flight		LCC-3UB	Solder dip	0.06	-
SOC37000	-	Eng. model		LCC-3	Gold	0.06	-
SOC3700SW	5201/004/05	ESCC flight	100 krad	LCC-3	Solder dip	0.06	Y
SOC3700HRB	5201/004/04 or 05	ESCC flight		LCC-3	Gold/Solder dip ⁽¹⁾	0.06	Y
2N3700T1	-	Eng. model		TO-18	Gold	0.40	-
2N3700HR	5201/004/01 or 02	ESCC flight		TO-18	Gold/Solder dip ⁽¹⁾	0.40	-

1. Depending ESCC part number mentioned on the purchase order

November 2011

1 Electrical ratings

Table 2	Absolute	maximum	ratings
	Absolute	maximum	raungs

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-base voltage $(I_E = 0)$	140	V
V _{CEO}	Collector-emitter voltage ($I_B = 0$)	80	V
V _{EBO}	Emitter-base voltage ($I_C = 0$)	7	V
۱ _C	Collector current	1	А
P _{tot}	Total dissipation at $T_{amb} \le 25$ °C for 2N3700HR for SOC3700HRB for SOC3700HRB ⁽¹⁾ Total dissipation at $T_c \le 25$ °C for 2N3700HR	0.5 0.5 0.76 1.8	w w w
T _{stg}	Storage temperature	-65 to 200	°C
Т _Ј	Max. operating junction temperature	200	°C

1. When mounted on a 15 x 15 x 0.6 mm ceramic substrate.

Table 3.	Thermal data	for through-hole	package

Symbol	Parameter	TO-18	Unit
R _{thJC}	Thermal resistance junction-case max	97	°C/W
R _{thJA}	Thermal resistance junction-ambient max	350	°C/W

Table 4. Thermal data for SMD package

Symbol	Parameter	SOC	Unit
R _{thJA}	Thermal resistance junction-ambient max	350	°C/W
R _{thJA}	Thermal resistance junction-ambient (1) max	230	°C/W

1. When mounted on a $15 \times 15 \times 0.6$ mm ceramic substrate.



2 Electrical characteristics

 T_{case} = 25 °C unless otherwise specified.

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{CBO}	Collector cut-off current (I _E = 0)	$V_{CB} = 90 V V_{CB} = 90 V T_{amb} = 110 °C T_{CB} = 90 V T_{amb} = 150 °C $			10 100 10	nA nA μA
I _{EBO}	Emitter cut-off current $(I_{C} = 0)$	V _{EB} = 5 V			10	nA
V _{(BR)CBO}	Collector-base breakdown voltage (I _E = 0)	l _C = 100 μA	140			V
V _{(BR)CEO} ⁽¹⁾	Collector-emitter breakdown voltage $(I_B = 0)$	I _C = 30 mA	80			V
V _{(BR)EBO}	Emitter-base breakdown voltage (I _C = 0)	l _E = 100 μA	7			v
V _{CE(sat)} ⁽¹⁾	Collector-emitter saturation voltage	$I_{C} = 150 \text{ mA}$ $I_{B} = 15 \text{ mA}$ $I_{C} = 500 \text{ mA}$ $I_{B} = 50 \text{ mA}$			0.2 0.5	V V
V _{BE(sat)} ⁽¹⁾	Base-emitter saturation voltage	$I_{C} = 150 \text{ mA}$ $I_{B} = 15 \text{ mA}$ $I_{C} = 150 \text{ mA}$ $I_{B} = 15 \text{ mA}$ $T_{amb} = 110 ^{\circ}\text{C}$	0.75 0.65	0.87 0.77	1 0.9	v v
h _{FE} ⁽¹⁾	DC current gain		90 100 50 40		300	
h _{fe}	Small signal current gain	V _{CE} = 10 V I _C = 50 mA f = 20 MHz	5			
C _{CBO}	Output capacitance $(I_E = 0)$	V _{CB} = 10 V f = 1 MHz			12	pF
C _{IBO}	Input capacitance (I _C = 0)	V _{EB} = 0.5 V f = 1 MHz			60	pF

 Table 5.
 Electrical characteristics

1. Pulsed duration = 300 $\mu s,\,duty\,cycle \leq$ 2 %

2.1 Electrical characteristics (curves)

lc(A)





AM09692v1

lc(A)



AM09693v1

2.2 Test circuit



Figure 6. Resistive load switching test circuit

1. Fast electronic switch

2. Non-inductive resistor



3 Package mechanical data

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Dim		mm.	
Dini.	Min.	Тур.	Max.
A	1.16		1.42
С	0.46	0.51	0.56
D	0.56	0.76	0.96
E	0.92	1.02	1.12
F	1.95	2.03	2.11
G	2.92	3.05	3.18
I	2.41	2.54	2.67
J	0.42	0.57	0.72
К	1.37	1.52	1.67
L	0.41	0.51	0.61
М	2.46	2.54	2.62
N	1.81	1.91	2.01
r		0.20	
r1		0.30	
r2		0.56	

Table 6. LCC-3UB mechanical data

Figure 7. LCC-3UB drawings





Dim		mm.	
Din.	Min.	Тур.	Max.
A	1.16		1.42
С	0.45	0.50	0.56
D	0.60	0.76	0.91
E	0.91	1.01	1.12
F	1.95	2.03	2.11
G	2.92	3.05	3.17
I	2.41	2.54	2.66
J	0.42	0.57	0.72
К	1.37	1.52	1.67
L	0.40	0.50	0.60
М	2.46	2.54	2.62
N	1.80	1.90	2.00
R		0.30	

 Table 7.
 LCC-3 mechanical data







Dim	mm.		
Dini.	Min.	Тур.	Max.
А		12.7	
В			0.49
D			5.3
E			4.9
F			5.8
G	2.54		
Н			1.2
I			1.16
L	45°		

Table 8.TO-18 mechanical data





4 Order codes

Table 9.Order codes

Order codes	ESCC Part number	Rad level	Packages	Lead Finish	Marking	EPPL	Packing
2N37000UB1	-		LCC-3UB	Gold	2N37000UB1	-	Waffle pack
2N37000UBSW	5201/004/07	100 krad	LCC-3UB	Solder Dip	520100407	Y	Waffle pack
2N37000UB06	5201/004/06		LCC-3UB	Gold	520100406	-	Waffle pack
2N37000UB07	5201/004/07		LCC-3UB	Solder Dip	520100407	-	Waffle pack
SOC37000	-		LCC-3	Gold	SOC3700	-	Waffle pack
SOC3700SW	5201/004/05	100 krad	LCC-3	Solder Dip	520100405	Y	Waffle pack
SOC3700HRB	5201/004/04 or 05		LCC-3	Gold or Solder Dip ⁽¹⁾	520100404 or 05	Υ	Waffle pack
2N3700T1	-		TO-18	Gold	2N3700T1	-	Strip pack
2N3700HR	5201/004/01 or 02		TO-18	Gold or Solder Dip ⁽¹⁾	520100401 or 02	-	Strip pack

1. Depending ESCC part number mentioned on the purchase order

Contact ST sales office for information about the specific conditions for:

- Products in die form
- Tape and reel packing



5 Revision history

Table 10.Document revision history

Date	Revision	Changes		
10-Jan-2008	1	Initial release		
07-Jan-2010	2	Modified Table 1 on page 1		
26-Jul-2010	3	Modified Table 1 on page 1, added Table 9 on page 10		
30-Nov-2011	4	 Modified: Table 5 on page 3 Added: Section 2.1: Electrical characteristics (curves) Minor text change in the document title on the coverpage 		



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